

Failure Analysis Probing Solutions

- Manual & Semiautomatic Versions
 - Single-Sided or Double-Sided
 - Die, partial wafers, whole wafers, wafers mounted on frames, packaged parts, modules, substrates, PCBs and more.
- Solutions for multiple materials and aspects of Failure Analysis:
 - Electrical – I-V, C-V, frequency, power consumption, signal integrity
 - Laser Cutter – single, dual, and triple frequency (Green, UV, IR) for metallization, passivation removal and blowing links
 - Emission Microscopy - mounted above or below the DUT
 - Thermal – from -60 C to 400 C using thermal chucks or thermal wand
- Shielded Enclosures - Dark Boxes or Localized Environmental Chambers (LEC)
- Manipulators – manual and programmable
- Probe Arms – coaxial, triaxial, kelvin, High Frequency, High Power and more
- Probe Tips, Probe Cards, Wedges
- Packaged Part Holders, Die Trays, Carrier Plates
- Integrated Solutions with Emission Microscopes, Laser Cutters, Thermal Chucks, Thermal Cameras, Test Instrumentation and more
- Modular PS4L Hardware & Software Architecture

